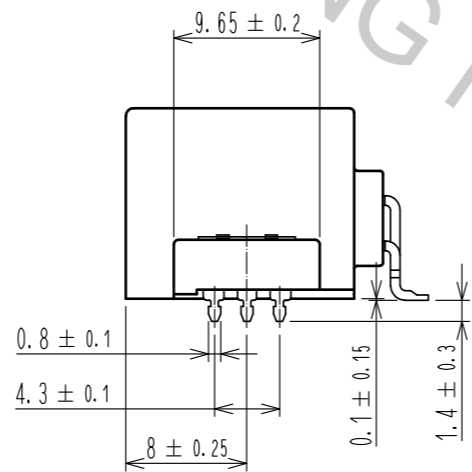
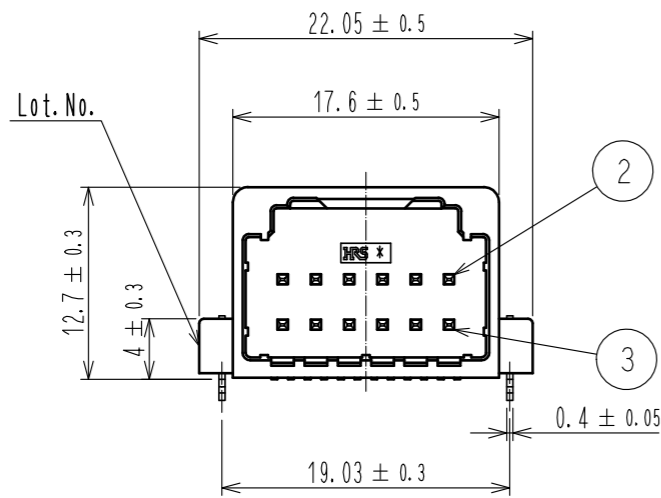
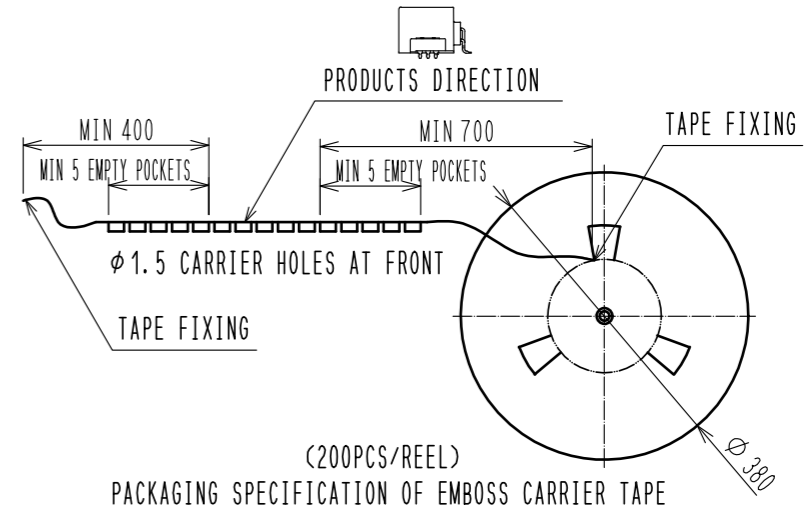
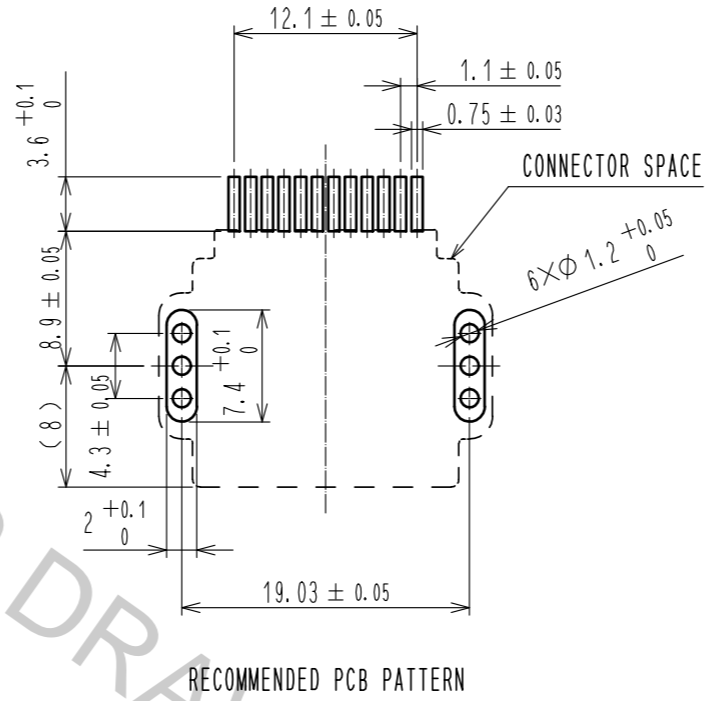
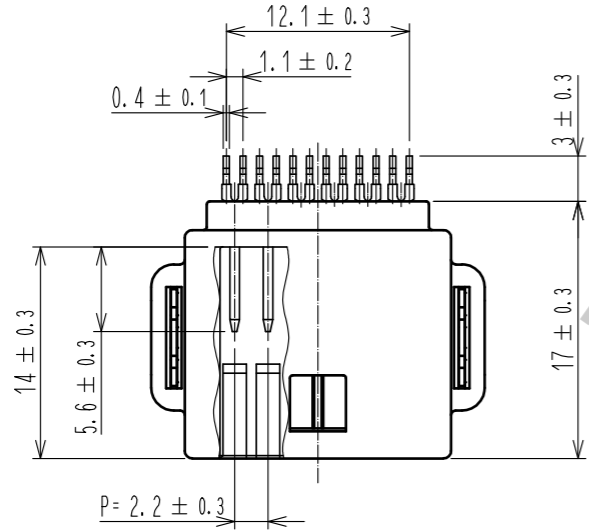
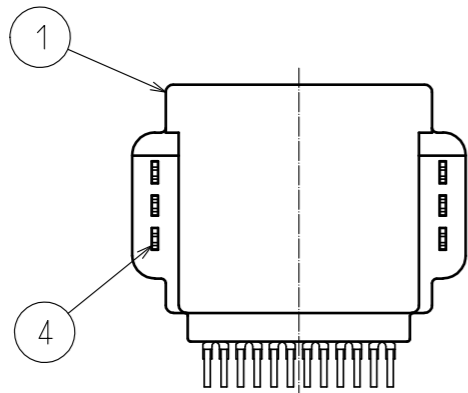
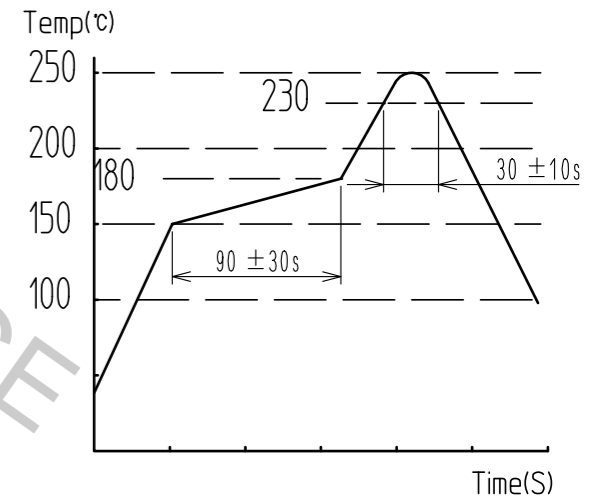


ELV, RoHS COMPLIANT

⚠ Add tolerance



- NOTE 1. RECOMMENDED TEMPERATURE PROFILE FOR REFLOW (REFER TO RIGHT FIG.)
 REFLOW HEATING METHOD : IR IN THE AIR OR NITROGEN
 NO. OF CYCLES : 2 MAX
 PEAK : 250°C
 OVER 230°C : 20~40s
 PREHEAT : 150~180°C 60~120s
2. TEMPERATURE FOR SOLDERING IRON : 280~300°C MAX WITHIN 2s
3. CO-PLANARITY SHALL BE 0.1mm MAX.
 4. PC BOARD THICKNESS = 1.6mm
 5. RECOMMENDED SOLDER THICKNESS = 0.15mm



2	BRASS	TIN PLATED T=0.64	4	BRASS	TIN PLATED T=0.4
1	PPS	LIGHT GRAY	3	BRASS	TIN PLATED T=0.64
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS	mm	SCALE	2 : 1	COUNT	1
		DESCRIPTION OF REVISIONS		DESIGNED	Y.T. HAYAKAWA
		DIS-T-00000894		CHECKED	NH. NAKATA
				DATE	16.01.28
APPROVED : KS. SATOH			07.03.05		
CHECKED : AR. SHIRAI			07.03.01		
DESIGNED : TY. SAKASHITA			07.03.01		
DRAWN : TY. SAKASHITA			07.03.01		
DRAWING NO.				EDC3-166407-00	
PART NO.				GT25-12DP-2.2H	
CODE NO.				CL775-0005-4-00	
				1/1	